



SOT974-2

plastic, thermal enhanced extremely thin small outline package; no leads; 16 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN3314-16
Package type industry code	DFN3314-16
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	25-3-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.2	-	3.3	3.4	mm
E	package width	1.25	-	1.35	1.45	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	



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2. Package outline

HXSON16: plastic, thermal enhanced extremely thin small outline package; no leads; 16 terminals; body 1.35 x 3.3 x 0.5 mm

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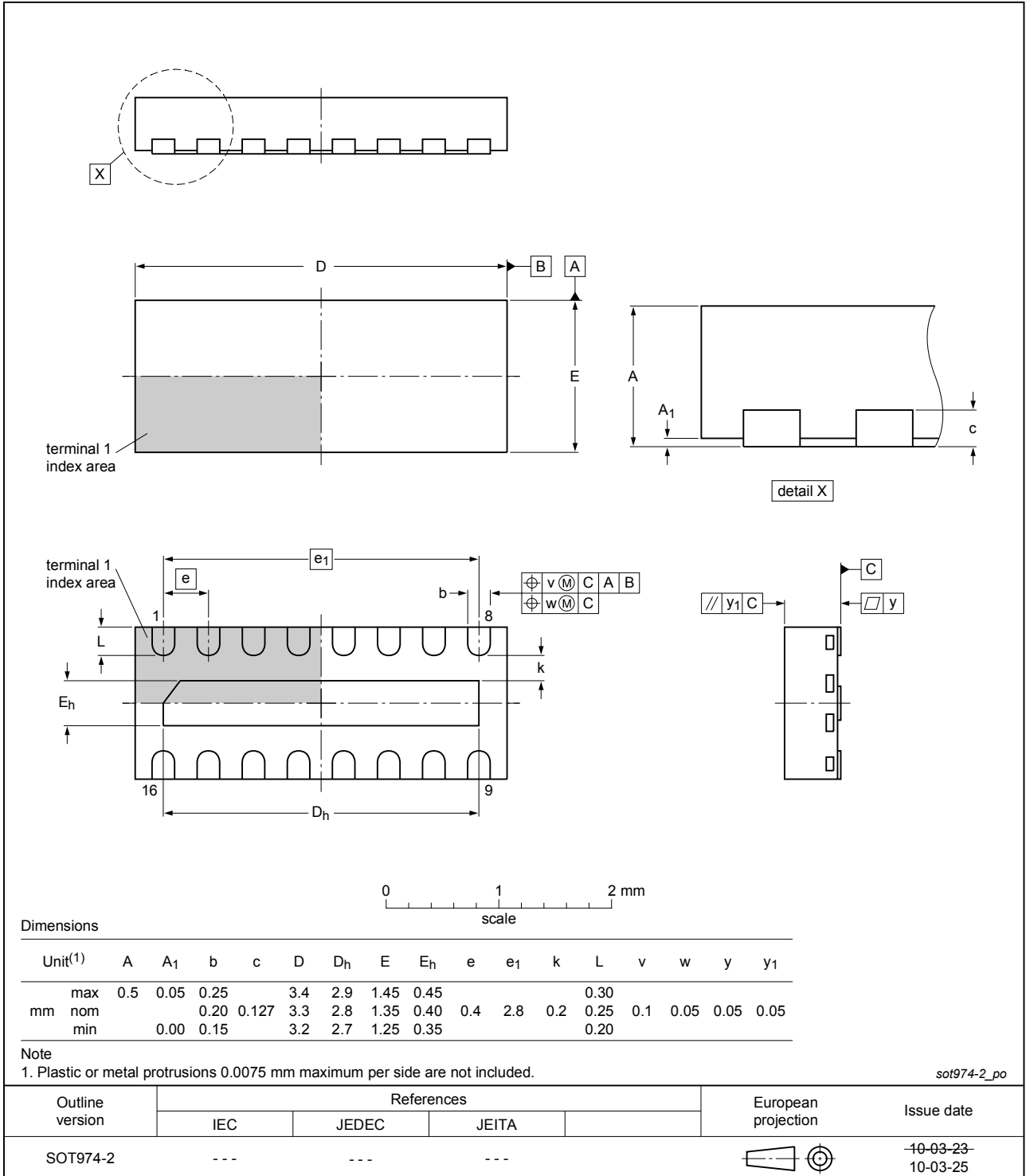


Fig. 1. Package outline DFN3314-16 (SOT974-2)

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3. Soldering

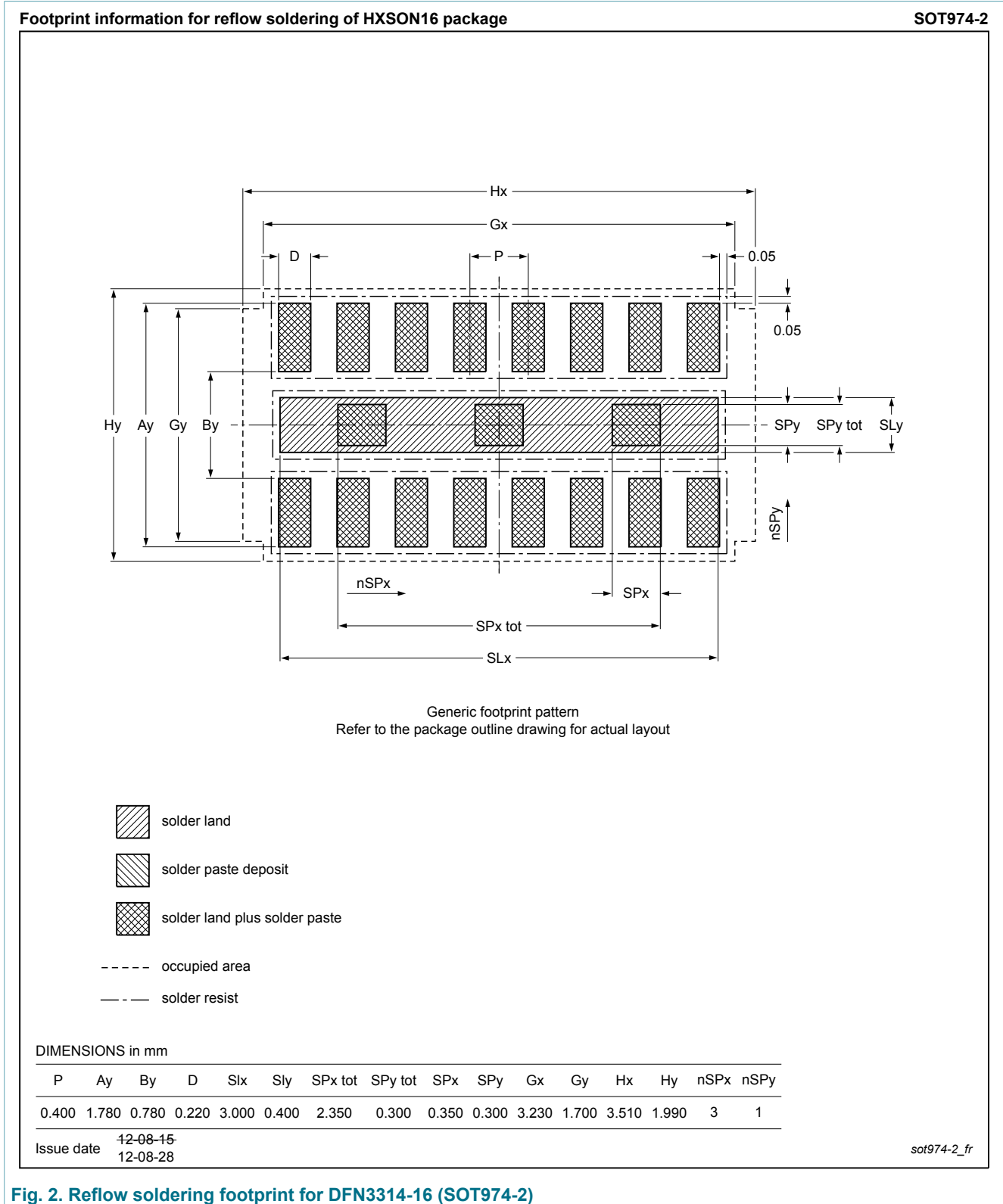


Fig. 2. Reflow soldering footprint for DFN3314-16 (SOT974-2)

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4. Legal information

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